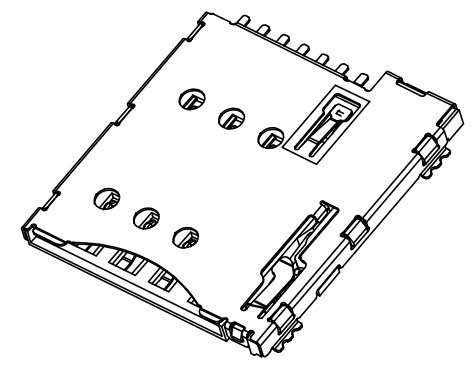
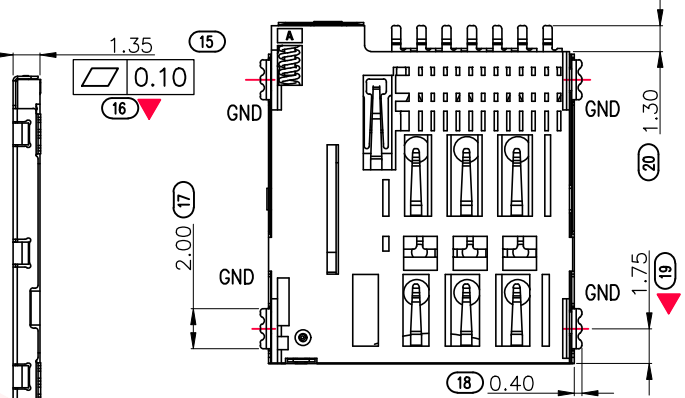
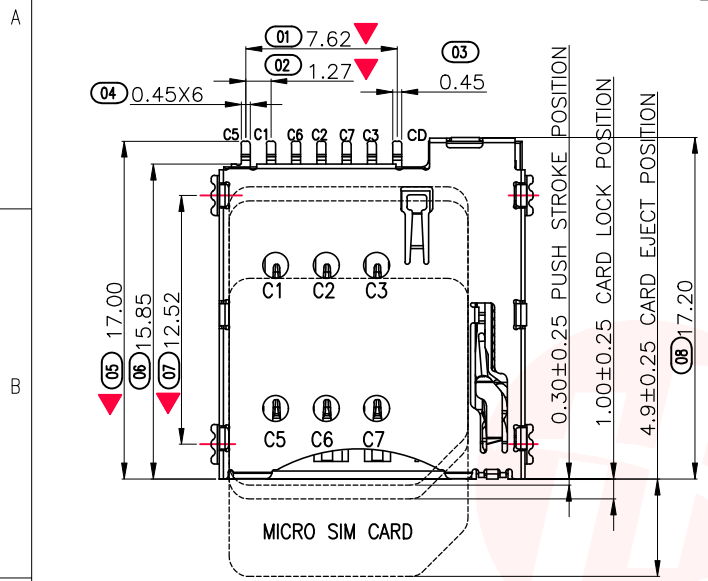




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



NOTES:

MATERIAL:

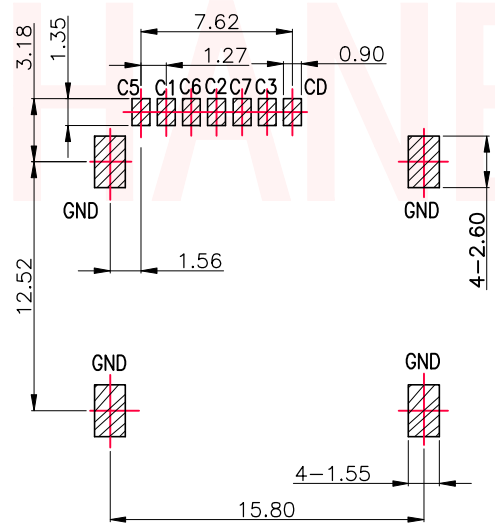
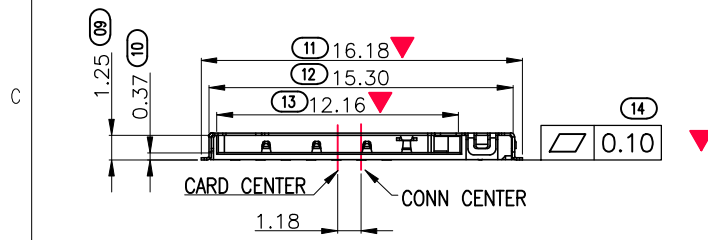
Insulator: High Temperature Thermoplastic, UL 94V-0.  
 Contact: Copper Alloy  
 Shell: STAINLESS

PLATING:

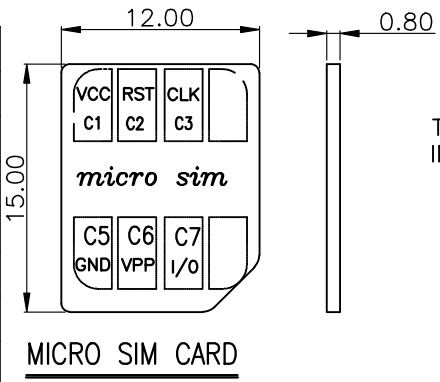
Contact: Plated 30u" Ni Overall ,Solder Area: Tin,Contact G/F  
 Shell: Plated 30u" Ni Overall  
 Plated G/F Selective Contact Area

Electrical:

Current Rating :0.5mA max.  
 Voltage Rating :50V DC MAX  
 Ambient Temperature Range :-20°C~+85°C  
 Storage Temperature Range :-40°C~+70°C  
 Ambient Humidity Range :95% R.H. Max.  
 Contact Resistance:100mΩ max.  
 Insulation Resistance:1000MΩ min./250V DC  
 Dielectric Withstanding Voltage:500V AC  
 Mating Cycles:5,000 Insertions  
 Temperature: 260°C ±5°



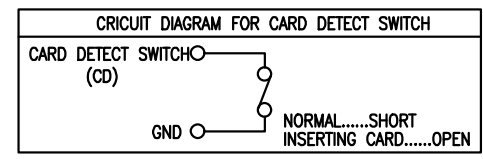
SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



■ CIRCUT TRACE KEEP OUT AREA  
 ■ SMT SOLDER AREA

THERE SHOULD NOT BE ANY CIRCUITRIES IN THE LAYOUT SPACE OF THE PRODUCTS.

RECOMMENDED PCB LAYOUT  
 GENERAL TOLERANCE ±0.05



UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.30	X :±2°
X.X :±0.20	X.X :±1°
X.XX :±0.10	

东莞市汉博电子科技有限公司  
 DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	MICRO SIM PUSH PUSH 1.35H 6+1PIN#CD PIN			
DWN	xiong	PART NO. SMO-222-P7		
CHKD	lee	SCALE:1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET:10F 1	REV: A4
CUSTOMER COPY				